

## NEXTREME FUNDS HEAT TRANSPORT RESEARCH AT THE UNIVERSITY OF WATERLOO

Nextreme partners with research pioneers in electronic heat transfer ...

**Research Triangle Park, N.C. (April 26, 2007)** – Nextreme, a leading manufacturer of advanced thermoelectric components that address thermal management and power generation needs of the semiconductor, photonics, test-and-measurement and defense/aerospace industries, announced research funding for the Microelectronics Heat Transfer Lab (MHTL), located at the University of Waterloo, Ontario, Canada. The MHTL program was created to implement Nextreme’s unique embedded thermoelectric component (eTEC™) technology in novel, system-level thermal management and power generation applications.

“MHTL is a pioneer in electronic heat transfer with a long history in design, implementation and testing of the most advanced heat transport methods”, said Jesko von Windheim, CEO of Nextreme, “We look forward to a strong and continued partnership as we strive to create ground-breaking thermal and power generation solutions at the system level.”

Nextreme has contributed more than C\$300,000 to development work at MHTL.

For more information about Nextreme’s involvement in the MHTL programs at the University of Waterloo, contact Nextreme at 3040 Cornwallis Road, P.O. Box 13981, Research Triangle Park, NC 27709-3981; call (919)-990-8300; e-mail [info@nextreme.com](mailto:info@nextreme.com); or go to [www.nextreme.com](http://www.nextreme.com).

### About Nextreme

Nextreme manufactures thin-film thermoelectric components that address most challenging thermal management and power generation needs of the semiconductor, photonics, consumer and defense/aerospace industries. Nextreme's miniature, thin-film eTEC offers an industry first — a micro-refrigerator the size of a piece of confetti that enables solid-state temperature control or power generation on a micro-scale, in close proximity source. eTECs operate as point-specific heat pumps for rapid cooling or heating of semiconductors and other electronics; for thermal management of fiber-optic laser controls integrated optoelectronics; or for power generation by converting otherwise wasted heat useful electricity.